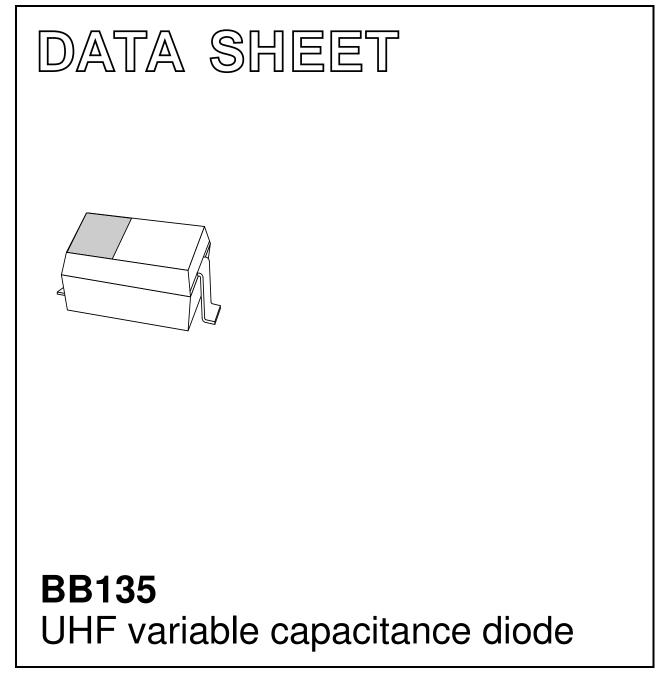
## DISCRETE SEMICONDUCTORS



Product specification Supersedes data of 1998 Sep 15 2004 Mar 01



### FEATURES

- Excellent linearity
- Very small plastic SMD package.
- C28: 1.9 pF; ratio: 10
- Low series resistance.

### APPLICATIONS

- Electronic tuning in UHF television tuners.
- Radio upconversion concepts
- VCO.

### DESCRIPTION

The BB135 is a variable capacitance diode, fabricated in planar technology, and encapsulated in the SOD323 very small plastic SMD package.

The matched type, BB134 has the same specification.

### PINNING

PIN	DESCRIPTION	
1	cathode	
2	anode	

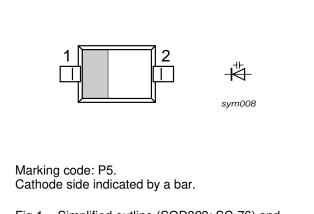


Fig.1 Simplified outline (SOD323; SC-76) and symbol.

### ORDERING INFORMATION

TYPE	PACKAGE		
NUMBER	NAME	DESCRIPTION	VERSION
BB135	-	<ul> <li>plastic surface mounted package; 2 leads</li> </ul>	

#### LIMITING VALUES

In accordance with the Absolute Maximum Rating System (IEC 60134).

SYMBOL	PARAMETER	MIN.	MAX.	UNIT	
V <sub>R</sub>	continuous reverse voltage	_	30	V	
I <sub>F</sub>	continuous forward current	_	20	mA	
T <sub>stg</sub>	storage temperature	-55	+150	°C	
Тį	operating junction temperature	-55	+125	°C	

## BB135

### ELECTRICAL CHARACTERISTICS

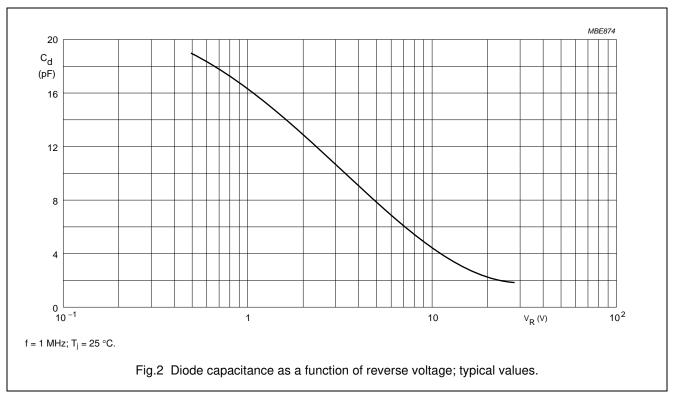
 $T_j$  = 25 °C unless otherwise specified.

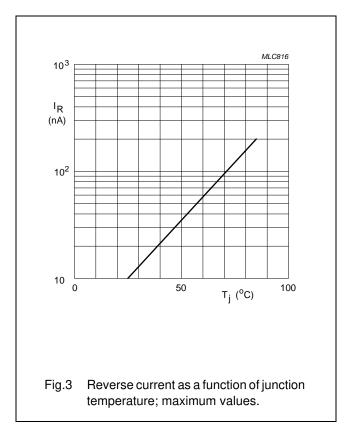
SYMBOL	PARAMETER	CONDITIONS	MIN.	MAX.	UNIT
I <sub>R</sub>	reverse current	V <sub>R</sub> = 30 V; see Fig.3	-	10	nA
		V <sub>R</sub> = 30 V; T <sub>j</sub> = 85 °C; see Fig.3	_	200	nA
r <sub>s</sub>	diode series resistance	f = 470 MHz; note 1	-	0.75	Ω
C <sub>d</sub>	diode capacitance	$V_R = 0.5 V$ ; f = 1 MHz; see Figs 2 and 4	17.5	21	pF
		$V_R = 28 V$ ; f = 1 MHz; see Figs 2 and 4	1.7	2.1	pF
$\frac{C_{d(0.5V)}}{C_{d(28V)}}$	capacitance ratio	f = 1 MHz	8.9	12	

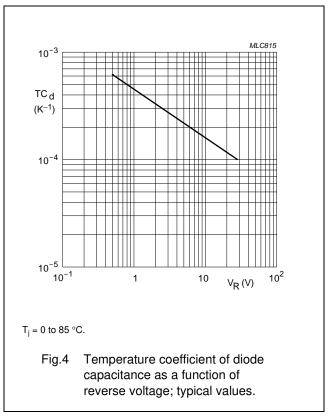
### Note

1.  $V_R$  is the value at which  $C_d = 9 \text{ pF}$ .

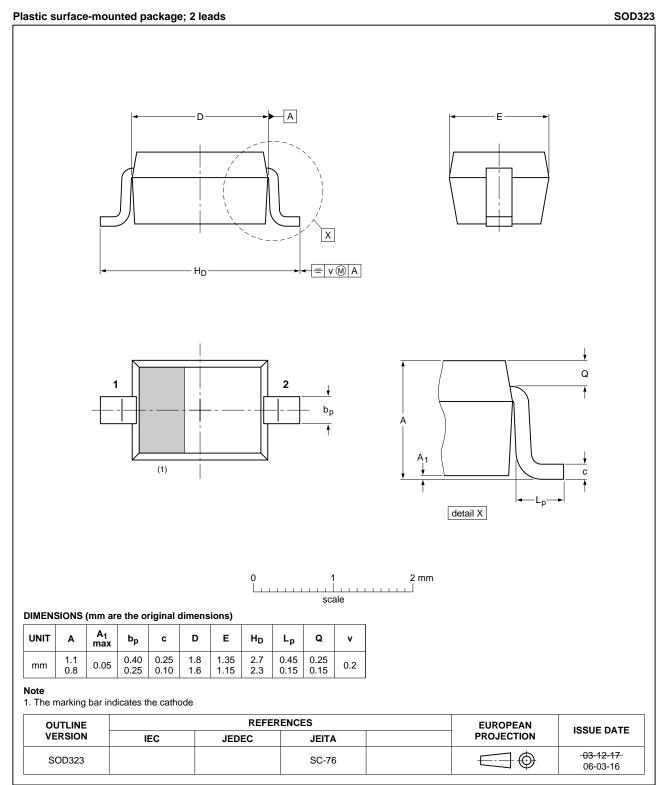
### **GRAPHICAL DATA**







### PACKAGE OUTLINE



### BB135

### DATA SHEET STATUS

DOCUMENT STATUS <sup>(1)</sup>	PRODUCT STATUS <sup>(2)</sup>	DEFINITION
Objective data sheet	Development	This document contains data from the objective specification for product development.
Preliminary data sheet	Qualification	This document contains data from the preliminary specification.
Product data sheet	Production	This document contains the product specification.

#### Notes

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#### **Customer notification**

This data sheet was changed to reflect the new company name NXP Semiconductors, including new legal definitions and disclaimers. No changes were made to the technical content, except for package outline drawings which were updated to the latest version.

#### **Contact information**

For additional information please visit: http://www.nxp.com For sales offices addresses send e-mail to: salesaddresses@nxp.com

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Printed in The Netherlands

R77/04/pp8

Date of release: 2004 Mar 01